

5

by reference numeral 14. SRAM 14 includes an emitter coupled logic (ECL) address input buffer 16 receiving address input $A_i, A_{i+1} \dots A_{i+n}$ from an address bus 18. The ECL input buffer 16 in turn outputs each address value A_x received from the address bus 18 together with its complement \bar{A}_x . Receiving the output of the ECL input buffer 16 is address conditioning circuitry 20. Circuitry 20 provides input to a row decoder and driver 22 as well as to a column decoder and driver 24. Word-lines (WLs) extend from the row decoder and driver 22 and lead to a memory cell array 26. Bit lines extend from the memory cell array 26 and lead to a bit line precharge circuit 28 as well as to a sense amplifier array and write circuitry 30. Each cell 26a in the memory cell array 26 is connected to one of the word lines and to consecutive bit lines Bit and $\bar{\text{Bit}}$ respectively. The sense amplifier array and write circuitry 30 is connected to the column decoder and driver 24 as well as to an ECL output buffer 32 by way of an amplifier 34. The ECL output buffer 32 is also connected to a data bus 36. A data input buffer 37 is also connected to the data bus 36 as well as to the sense amplifier array and write circuitry 30 by way of a level converter 38. A control and bias generator 39 is included in the SRAM 14 to control whether data is to be read from or written to the memory cell array 26.

FIG. 2 better illustrates the address conditioning circuitry 20 and the row decoder and driver 22. As can be seen, address conditioning circuitry 20 includes an ECL wired-OR (W-OR) predecoder array 40 connected to the ECL input buffer 16 as well as to a level translator array 42. The level translator array 42 provides block select and word select line inputs to self-resetting word-line decoder and driver (WLDD) circuits 44 (best seen in FIGS. 5 and 6) constituting the row decoder and driver 22. The output of the WLDD circuits 44 is applied to the word-lines WL_x leading to the memory cell array 26. The level translator array 42 also provides input to the column decoder and driver 24.

In operation, when it is desired to read data from the memory cell array 26 and an address is received by the ECL input buffer 16, the address information is predecoded and translated before being supplied to the row and column decoder and drivers 22 and 24 respectively. The row decoder and driver uses the address information to select the desired memory cells 26a corresponding to the received address information. The column decoder and driver 24 uses the address information to activate the sense amplifiers associated with the selected memory cells 26a so that the sense amplifiers can sense the state of the memory cells. The sense amplifiers in turn supply output representing the sensed state of the activated memory cells to the ECL output buffer 32 via amplifier 34.

When it is desired to write data to the memory cell array 26 and an address is received by the ECL input buffer 16, a similar process is carried out with the exception that the column decoder and driver 24 activates the write circuitry associated with the selected memory cells 26a. The write circuitry receives data to be written to the memory cells 26a via input buffer 37 and level converter 38 and writes the data to selected memory cells.

The general operation of SRAM 14 is conventional. However, the design of the SRAM 14 is such to reduce power consumption while maintaining memory cell access speed. In order to reduce power consumption novel circuitry in the W-OR predecoder, level translator and sense amplifier arrays as well as in the WLDD circuits constituting the row decoder and driver 22 has been designed and will now be described.

Referring now to FIG. 3, an embodiment of a W-OR predecoder 50 and level translator 52 forming part of the

6

arrays 40 and 42 respectively is shown. As can be seen, W-OR predecoder 50 includes a pair of transistors 56 and 58. The collectors of the transistors 56 and 58 are coupled and lead to a positive voltage source V_p . The base of transistor 58 is connected to the bit A_i output of the ECL input buffer 16 and the base of transistor 56 is connected to the bit A_{i+1} output of the ECL input buffer 16. The emitters of the transistors 56 and 58 are also coupled and lead to the anode of a diode 60. The cathode of the diode 60 is connected to ground V_n through a resistor 62. The diode 60 and resistor 62 form the pull-down circuitry of the W-OR predecoder 50. The W-OR predecoder 50 also includes a logic output line 64 and two drive lines 66 and 68 respectively.

The level translator 52 is in the form of a single source follower and since it directly follows the W-OR predecoder 50, no problems arise as a result of using the two drive lines 64 and 66 respectively. Specifically, the level translator 52 includes a PMOS field effect transistor (FET) 70, an NMOS FET 72, an inverter 74 and a capacitor 76. FET 70 has its drain connected to output line 64 and its gate connected to the drive line 64. The source of FET 70 is connected to the inverter 74 as well as to the drain of FET 72. FET 72 has its gate connected to the drive line 68 and its source connected to ground V_n . The capacitor 76 has one terminal connected between the inverter 74 and the output node V_o of the level translator 52 and another terminal connected to ground V_n . The level translator 52 ensures that the output of the W-OR predecoder 50 is at CMOS levels. The inverter 74 ensures full-signal restoration and functions as a pre-driver for the following word-line decoder and driver circuit 44.

In operation, when the inputs A_i and A_{i+1} are both low, the two transistors 56 and 58 respectively are off and the potential on output line 64 is high and equal to the voltage source V_p . The potential on drive lines 66 and 68 is low turning FET 70 on and FET 72 off. Thus, the high potential on output line 64 is applied to inverter 74 through FET 70 resulting in a logic low output on output node V_o .

When either one or both inputs A_i and A_{i+1} is high, one or both of the transistors 56 and 58 is on. This results in the drive line 66 becoming coupled to the voltage source V_p through one or both of the transistors placing a high potential on the drive line 66. This causes FET 70 to turn off. When one or both of the transistors 56 and 58 is on, drive line 68 also becomes coupled to the voltage source V_p through one or both of the transistors as well as through diode 60. This causes FET 72 to turn on. Therefore, the inverter 74 becomes coupled to ground through FET 72 resulting in a logic high output on output node V_o .

The logic output on output node V_o is supplied to either a block select line or word select line input of one of the WLDD circuits 44. Therefore, depending on the logic value inputs A_x and A_{x+1} to the various W-OR predecoders 50 in the array 40, different logic values are supplied to the various block select line and word select line inputs to the WLDD circuits 44. This allows selected blocks of the memory cell array 28 to be activated.

FIG. 4 shows the output of the W-OR predecoder 50 and level translator 52 under column $A_i + A_{i+1}$ for the various values of logic inputs A_i and A_{i+1} . Since the ECL input buffer 16 generates two address outputs A_x and \bar{A}_x for each address input A_x , four W-OR predecoders 50 and level translators 52 of the type shown in FIG. 3 are necessary to generate the logic outputs under the four columns of the table illustrated in FIG. 4.

Because the diode 60 level shifts the input signal to the FET 72 when the FET is turned on and because the level